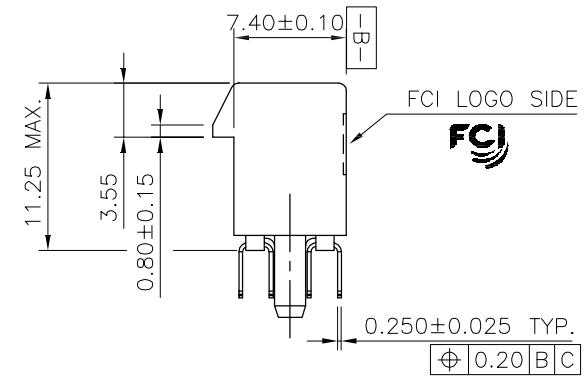
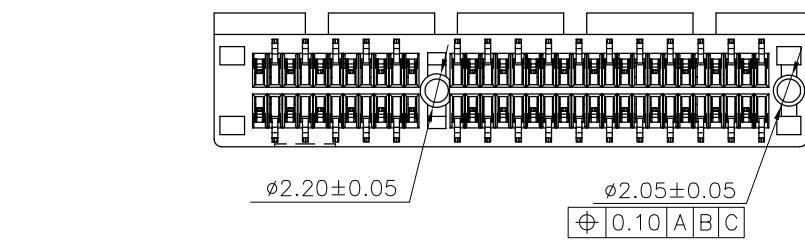
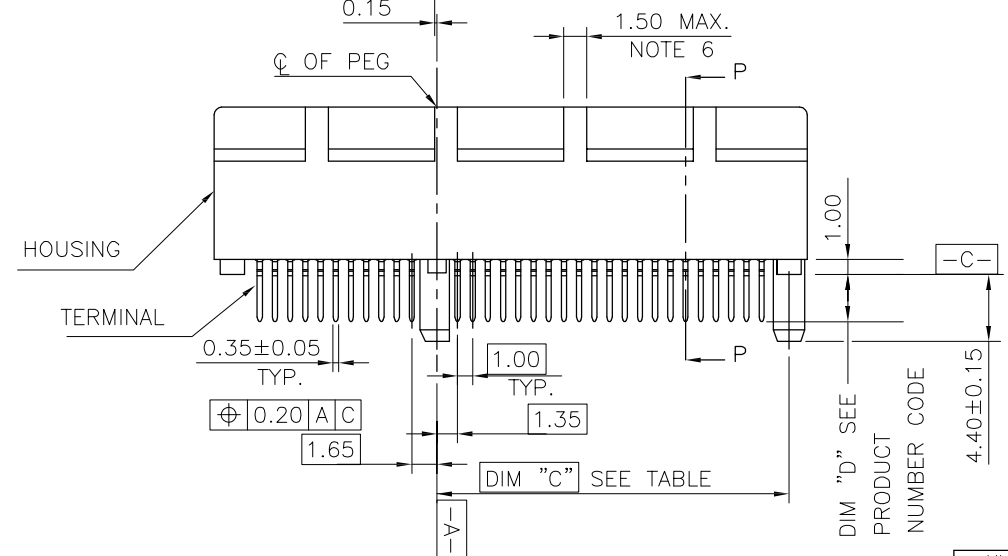
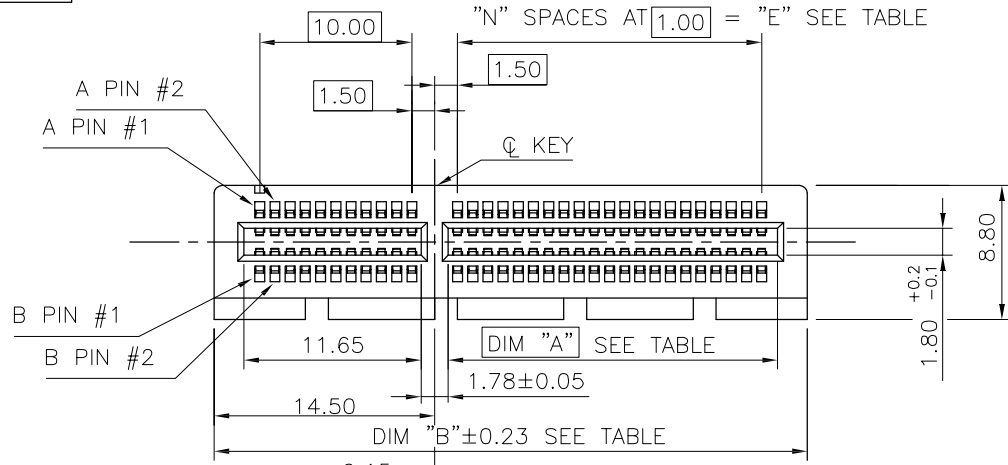


PRODUCT NO.
10108777-X0XXXX



TWIN PLASTIC PEG TYPE

mat'l. code		surface		tolerance		projection		product family	
-		-		ASME_Y14.5		MM		PCI_EXPRESS	
tolerances unless otherwise specified									
lfr	ecn no	dr	date	angles	LineGr	MM		title	
C	DG-011582	HT	5/10/12		.02±0.30			PCI_EXPRESS_CARD_EDGE_GEN3	
D	ELX-DG-013209	WL	07/24/12		.00±0.20			TH_ASS'Y	
E	ELX-DG-2181-1	ST	05/27/15		±2'	scale N/A		dwg no	
F	ELX-DG-24164	ZH	05/30/16	dr	ZHENHUA_LIU	2016-03-30		sheet 1 of 7	
G	ELX-DG-25671	ZH	12/18/16	enfr	ZHENHUA_LIU	2016-03-30		size	
H	ELX-DG-27937	ZH	09/12/17	chr	STONE_LI	2016-03-30		10108777	
						Amphenol FCI		CUSTOMER Drawing	
sheet index		revision sheet		H					

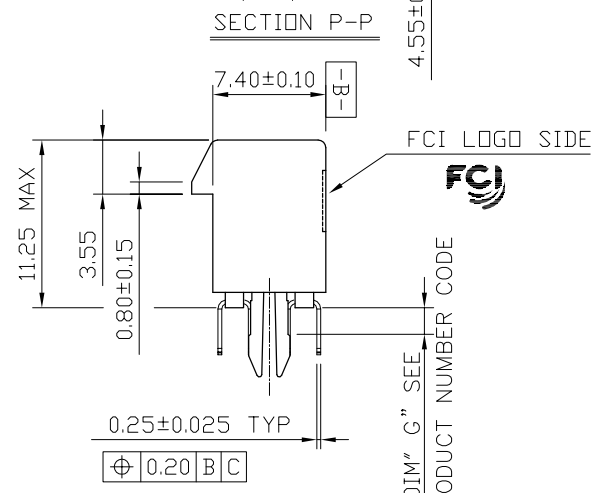
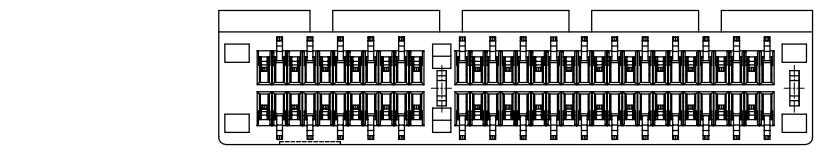
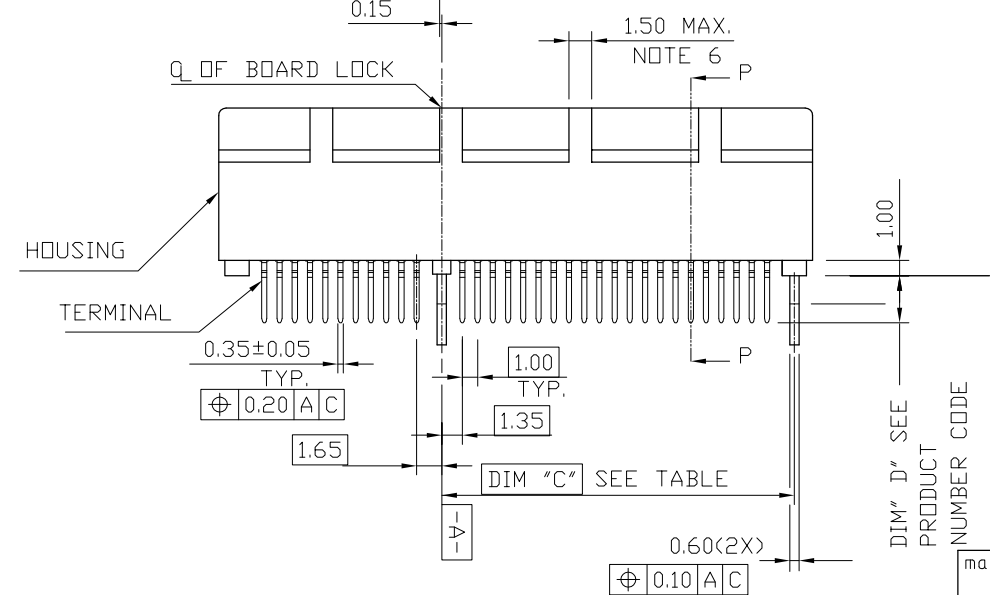
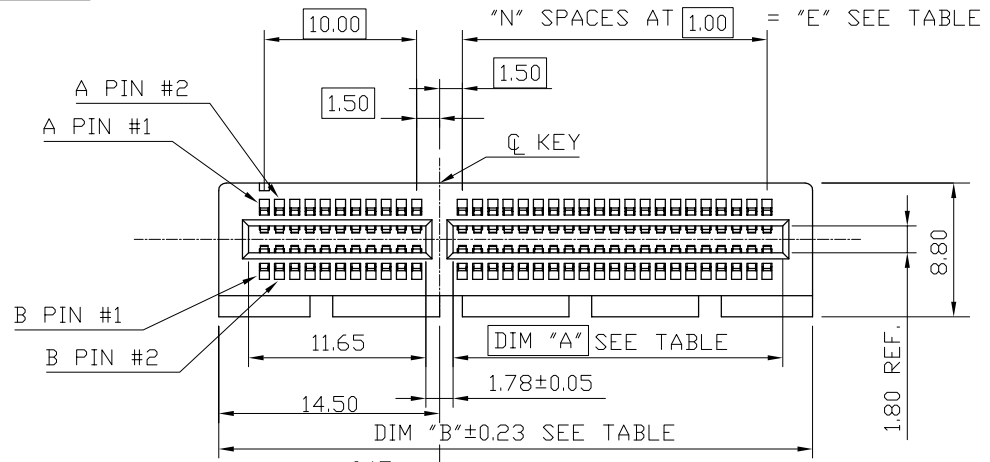
PRODUCT NO.
10108777-X2XXXX



SINGLE PLASTIC PEG TYPE

mat'l. code		-		surface		- ✓		tolerance		ASME_Y14.5		projection		product family		PCI_EXPRESS	
lfr		ecn no		dr		date		tolerances unless otherwise specified		angles		MM		title		PCI_EXPRESS_CARD_EDGE_GEN3	
								±2'		LineGr		scale N/A		TH_ASS'Y		5	
				dr		ZHENHUA_LIU		2016-03-30		Amphenol FCI		dwg no		sheet 2 of 7		size	
				enfr		ZHENHUA_LIU		2016-03-30				10108777				A4	
				chr		STONE_LI		2016-03-30				type		CUSTOMER Drawing		B	
				appd		PM_ZHENG		2016-03-30									
sheet index		revision sheet		H													

PRODUCT NO.
10108777-X1XXXX



METAL BOARD LOCKS

mat'l. code		surface		tolerance	projection	product family	
-		-		ASME_Y14.5	MM	PCI_EXPRESS	
lfr		ecn no	dr	date		title	
					PCI_EXPRESS_CARD_EDGE_GEN3		
					TH_ASS'Y		
					dwg no		
					sheet 3 of 7		
					size		
					A4		
					type		
					CUSTOMER Drawing		
sheet index		revision sheet		H			



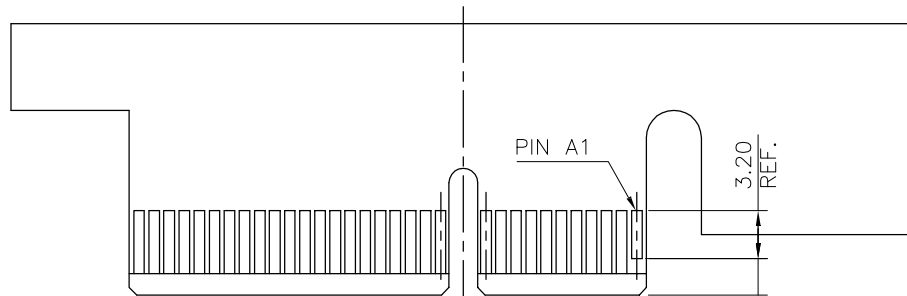
RECOMMENDED FOOTPRINT

mat'l. code		surface		tolerance		projection		product family	
-		-		ASME_Y14.5				PCI_EXPRESS	
lfr		ecn no		dr		date		title	
								PCI_EXPRESS_CARD_EDGE_GEN3	
								TH_ASS'Y	
								sheet 4 of 7	
								size	
								A4	
								type	
								CUSTOMER Drawing	
sheet index		revision sheet		H					



SCALE 2:1

← I/O PANEL DIRECTION
PRIMARY (COMPONENT) SIDE



I/O PANEL DIRECTION →
SECONDARY (SOLDER) SIDE

PIN "F" SEE TABLE 2.40±0.10 NOTE 4

PIN "F" SEE TABLE 2.40±0.10 NOTE 4

#	POS REF.	N	DIM "G"	"F"
36		6	8.15	B17
64		20	22.15	B31
98		37	39.15	B48
164		70	72.15	B81

ADD-IN CARD EDGE-FINGER DIMENSIONS

mat'l. code		surface		tolerance		projection		product family	
-		-		ASME_Y14.5				PCI_EXPRESS	
lfr		ecn no		dr		date		tolerances unless otherwise specified	
								title	
								PCI_EXPRESS_CARD_EDGE_GEN3	
								TH_ASS'Y	
								scale N/A	
								dwg no	
								sheet 5 of 7	
								size	
								A4	
								type	
								CUSTOMER Drawing	
sheet index		revision sheet		H					

NOTES:

1.MATERIAL:

HOUSING: HIGH TEMPERATURE NYLON, GLASS FILLED UL94V-0 RATED.
TERMINAL: COPPER ALLOY.

PLATING: 50u" NICKEL UNDERPLATE ALL OVER
CONTACT AREA PLATING - SEE PRODUCT NUMBER CODE
SOLDER TAIL: TIN OR TIN /LEAD(90/10)- SEE PRODUCT NUMBER CODE 100u" MIN. OVER 50u" NICKEL.

METAL BOARD LOCKS: COPPER ALLOY.
FINISH: 100u" TIN OR TIN/LEAD(90/10) OVER 50u" NICKEL
UNDERPLATE SEE PRODUCT NUMBER CODE.

2.PRODUCT SPECIFICATION: GS-12-233.

③THE HORIZONTAL AXIS FOR THE HOLE PATTERN IS ESTABLISHED BY

A LINE THROUGH THE CENTER OF THE TWO Ø2.35 HOLES.
THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER OF DATUM Z.

④NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND PIN NUMBERS "F".

⑤CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

⑥FREQUENCY & LOCATION AT SUPPLIER DISCRETION. RIDGE MAY BE CONTINUOUS WITH NO BREAKS.

7.RoHS COMPATIBLE PRODUCT SPECIFICATIONS:

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2um MINIMUM MATTE TIN OVER 1.27um MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY:

- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C TEMPERATURE FOR 10 SECONDS IN RE-FLOW APPLICATION, SEE NOTE 8 FOR APPLICATION.

PRODUCT NUMBER CODE

10108777 -X X X X X X

HOUSING COLOR OPTIONS

- 0-NATURAL
- 1-BLACK

PEGS OPTIONS

- 0-PLASTIC PEGS, DIM
- 1-METAL BOARD LOCKS
- 2-SINGLE PLASTIC PEGS

TERMINAL PLATING OPTIONS

- 0-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN TAIL AREA ----- COMPATIBLE RoHS
- 1-50u" Ni UNDERPLATE
15u" Au CONTACT AREA
100u" TIN TAIL AREA ----- COMPATIBLE RoHS
- 2-50u" Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN TAIL AREA ----- COMPATIBLE RoHS
- 3-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN/LEAD TAIL AREA ---INCOMPLIANT RoHS
- 4-50u" Ni UNDERPLATE
15u" Au CONTACT AREA
100u" TIN/LEAD TAIL AREA ---INCOMPLIANT RoHS
- 5-50u" Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN/LEAD TAIL AREA ---INCOMPLIANT RoHS

LEAD FREE OPTION

LEAVE BLANK FOR TERMINAL PLATING 3.4.5
"LF" FOR TERMINAL PLATING OPTION 0,1,2

POS OPTIONS

- 0-36
- 1-64
- 2-98
- 3-164

TAIL LENGTH OPTIONS

	DIM "D"	PCB THICKNESS	DIM "G"
0	2.30 ^{+0.25} / _{-0.13}	1.56±0.10	1.70±0.15
1	3.10 ^{+0.25} / _{-0.13}	2.36±0.10	2.50±0.15
2	2.54±0.25	1.56±0.10	1.70±0.15
3	1.90±0.25	1.56±0.10	1.70±0.15
4	3.10 ^{+0.25} / _{-0.13}	2.0±0.10	1.70±0.15

CONNECTOR	# POS REF.	N	DIM "A"	DIM "B"	DIM "C"	"E"
1 PORT	36	6	7.65	25.00	9.15	6.00
4 PORT	64	20	21.65	39.00	23.15	20.00
8 PORT	98	37	38.65	56.00	40.15	37.00
16 PORT	164	70	71.65	89.00	73.15	70.00

- 8.AN ADEQUATE PROCEDURE SET FORTH IN THE FOLLOWING ENSURE THAT THE PRODUCT RELIABILITY CAN BE ACHIEVED DURING AND AFTER PCB ASSEMBLY OPERATION.
- 8.1IF PARTIAL LOT ARE USED, THE REMAINING CONNECTORS MUST BE RESEALED AND PLACED IN SAFE STORAGE WITHIN SIX HOURS OF BAG OPENING.
- 8.2THE SAFE STORAGE CONDITION IS RECOMMENDED AT 25°C, 40%RH.
- 8.3NOT FOLLOWING THE PROCEDURE MAY CAUSE BLISTER DAMAGE DURING RE-FLOW PROCESS.
- 8.4IF BAKING IS REQUIRED, CONNECTOR SHALL BE BAKED FOR 4 HOURS AT 125°C.
- 8.5REFERENCE SPECIFICATION: IPC/JEDEC J-STD-033A.

PACKAGING OPTIONS

- E-HARD TRAY WITH MYLAR FOR VACUUM PACKAGING (FOR 164P ONLY)
- T-SOFT TRAY PACKAGING
- C-SOFT TRAY PACKAGING WITH 10MM CAP
- M-SOFT TRAY PACKAGING & MYLAR TAPE. SEE FIGURE 1
- Y-HARD TRAY PACKAGING (FOR 36P,98P AND 164P ONLY)
- Z-HARD TRAY PACKAGING WITH MYLAR (FOR 36P,98P AND 164P ONLY)
- H-SMALLER HARD TRAY PACKAGING WITH 30MM CAP (323X136X17.7 FOR 164P ONLY)
- △ Q-SMALLER HARD TRAY PACKAGING (323X136X17.7 FOR 164P ONLY)
- R-TAPE & REEL PACKAGING WITHOUT MYLAR (FOR 34, 64, 98P ONLY)
- W-TAPE & REEL PACKAGING WITHOUT MYLAR (FOR 98P ONLY), WITH 18.0MM CAVITY WIDTH
- A-TAPE & REEL PACKAGING WITH MYLAR (FOR 36, 64, 98P ONLY)

mat'l. code		surface		tolerance		projection		product family	
-		-		ASME_Y14.5				PCI_EXPRESS	
lfr		ecn no		dr		date		title	
								PCI_EXPRESS_CARD_EDGE_GEN3	
								TH_ASS'Y	
								dwg no	
								sheet 6 of 7	
								size	
								A4	
								type	
								CUSTOMER Drawing	
sheet index		revision		H					



POSTION OF MYLAR



POSTION OF CAP (10×10)



POSTION OF 30MM CAP(30X12)

mat'l. code		-		surface	-	tolerance	ASME_Y14.5	projection	product family	PCI_EXPRESS	
lfr	ecn no	dr	date	tolerances unless otherwise specified				title	PCI_EXPRESS_CARD_EDGE_GEN3		
				angles	±2'	linear	.02±0.30 .00±0.20 .000±0.10	MM	TH_ASS'Y		
								scale N/A	sheet 7 of 7 size		
		dr	ZHENHUA_LIU	2016-03-30				Amphenol FCI	dwg no		
		enfr	ZHENHUA_LIU	2016-03-30					10108777		
		chr	STONE_LI	2016-03-30					A4		
		appd	PM_ZHENG	2016-03-30					CUSTOMER Drawing		
sheet index	revision sheet	H									

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: org@lifeelectronics.ru